PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|-----------------|----------------|
| YI-CHENG LI | 07/27/2017 |
| CHIEN-HAO CHEN | 07/27/2017 |
| YUNG-CHENG LU | 07/27/2017 |
| JR-JUNG LIN | 07/31/2017 |
| CHUN-HUNG LEE | 07/28/2017 |
| CHAO-CHENG CHEN | 08/02/2017 |

RECEIVING PARTY DATA

| Name: | TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. |
|-----------------|--|
| Street Address: | NO. 8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK |
| City: | HSINCHU |
| State/Country: | TAIWAN |
| Postal Code: | 300-78 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 15670401 |

CORRESPONDENCE DATA

Fax Number: (703)205-8050

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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tu.t.tan@bskb.com, mailroom@bskb.com Email: BIRCH, STEWART, KOLASCH & BIRCH, LLP Correspondent Name: Address Line 1: 8110 GATEHOUSE ROAD, SUITE 100E

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| ATTORNEY DOCKET NUMBER: | 0941-3598PUS1 |
|-------------------------|---------------|
| NAME OF SUBMITTER: | TAN T. TU |
| SIGNATURE: | /Tan T. Tu/ |
| DATE SIGNED: | 08/07/2017 |

Total Attachments: 4

PATENT REEL: 043229 FRAME: 0583

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PATENT REEL: 043229 FRAME: 0584



ASSIGNMENT

WHEREAS, Yi-Cheng LI, Chien-Hao CHEN, Yung-Cheng LU, Jr-Jung LIN, Chun-Hung LEE, and Chao-Cheng CHEN

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD FOR FORMING SEMICONDUCTOR DEVICE STRUCTURE WITH GATE STRUCTURE

| Filed: | August 07, 20 | Serial No. 15/670,401 |
|-------------|---------------|--|
| Executed of | on: | y 27, 2017; July 28, 2017; and July 31, 2017 |

WHEREAS, <u>Taiwan Semiconductor Manufacturing Co., Ltd.</u>, of <u>No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C.</u>, hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

yelizii 17/08/02 17:33:55

ASSIGNMENT

| Date | Name: Yi-Cheng LI |
|-----------|-----------------------|
| Date | Name: Chien-Hao CHEN |
| Date | Name: Yung-Cheng LU |
| Date | Name: Jr-Jung LIN |
| Date | Name: Chun-Hung LEE |
| Pate 2017 | Name: Chao-Cheng CHEN |

ASSIGNMENT

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NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

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IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

P20171145US00/0503-B32303-US

ASSIGNMENT

| 2017/7/27 | Name: Yi-Cheng LI |
|---------------------------------|----------------------------------|
| Date | Name: Y1-Cheng EI |
| $\frac{2/2}{\text{Date}} / 201$ | Mame: Chien-Hao CHEN |
| <u>Jo17/7/27</u> Date | Name: Yung-Cheng LU |
| >0 7 / 1/31 Date | Jr Juny Lil Name: Jr-Jung LIN |
| >c")/7/>d Date | Name: Chun-Hung LEE |
| >=17/2/28 Date | Name: Chao-Cheng CHEN |
| Duto | Name. Chao-Cheng Chen |